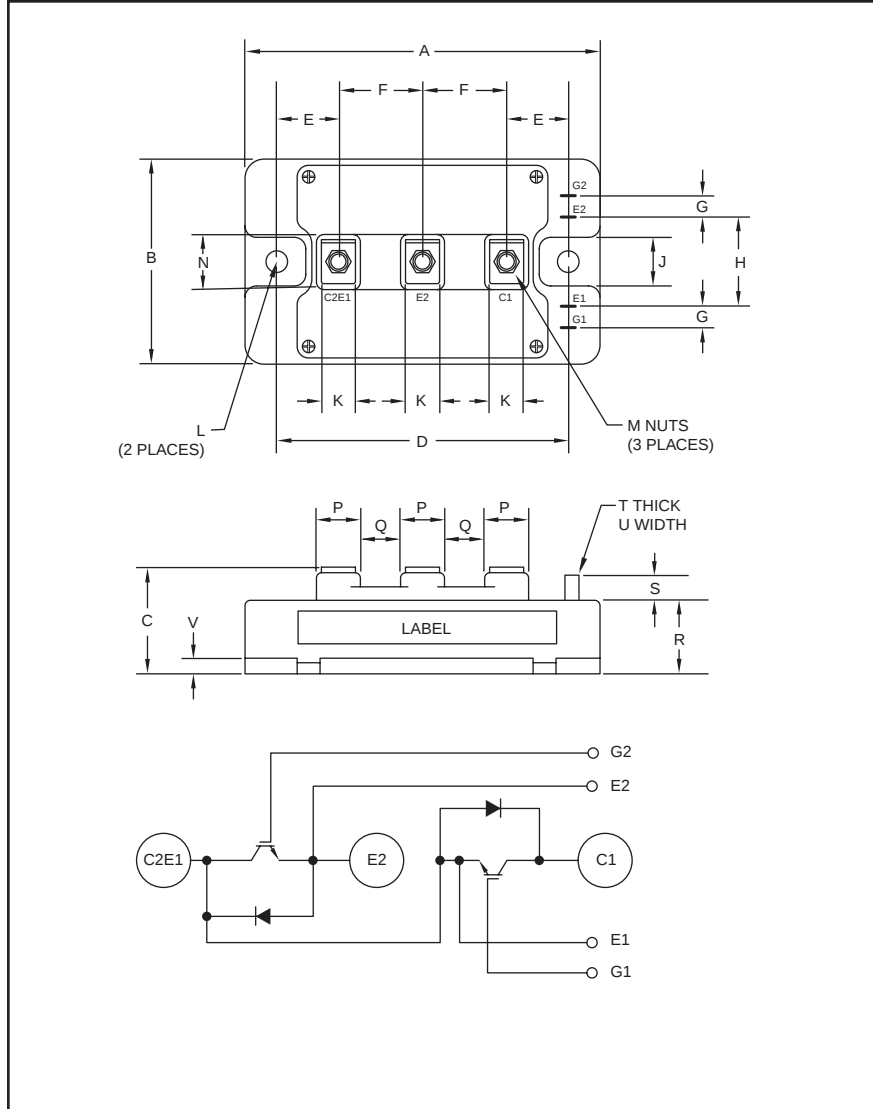


Dual IGBTMOD™ A-Series Module 75 Amperes/1700 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	3.70	94.0
B	1.89	48.0
C	1.14+0.04/-0.02	29.0+1.0/-0.5
D	3.15±0.01	80.0±0.25
E	0.67	17.0
F	0.91	23.0
G	0.16	4.0
H	0.71	18.0
J	0.51	13.0
K	0.47	12.0

Dimensions	Inches	Millimeters
L	0.26 Dia.	Dia. 6.5
M	M5 Metric	M5
N	0.79	20.0
P	0.63	16.0
Q	0.28	7.0
R	0.83	21.2
S	0.30	7.5
T	0.02	0.5
U	0.110	2.8
V	0.16	4.0



Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- ☐ Low Drive Power
- ☐ Low $V_{CE(sat)}$
- ☐ Discrete Super-Fast Recovery Free-Wheel Diode
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:

- ☐ AC Motor Control
- ☐ UPS
- ☐ Battery Powered Supplies

Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM75DY-34A is a 1700V (V_{CES}), 75 Ampere Dual IGBTMOD™ Power Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	75	34

CM75DY-34A
Dual IGBTMOD™ A-Series Module
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Absolute Maximum Ratings, $T_j = 25^\circ\text{C}$ unless otherwise specified

Ratings	Symbol	CM75DY-34A	Units
Junction Temperature	T_j	-40 to 150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E Short)	V_{CES}	1700	Volts
Gate-Emitter Voltage (C-E Short)	V_{GES}	± 20	Volts
Collector Current (DC, $T_C = 111^\circ\text{C}$)* ⁴	I_C	75	Amperes
Peak Collector Current (Pulse, Repetitive)* ²	I_{CM}	150	Amperes
Maximum Collector Dissipation ($T_C = 25^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$)* ^{2,4}	P_C	780	Watts
Emitter Current ($T_C = 25^\circ\text{C}$)* ²	I_E^{*1}	75	Amperes
Peak Emitter Current (Pulse, Repetitive)* ²	I_{EM}^{*1}	150	Amperes
Mounting Torque, M5 Main Terminal	—	30	in-lb
Mounting Torque, M6 Mounting	—	40	in-lb
Weight	—	310	Grams
Isolation Voltage (Main Terminal to Baseplate, $f = 60\text{Hz}$, AC 1 min.)	V_{ISO}	3500	Volts

Static Electrical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{\text{CE}} = V_{\text{CES}}$, $V_{\text{GE}} = 0\text{V}$	—	—	1.0	mA
Gate Leakage Current	I_{GES}	$V_{\text{GE}} = V_{\text{GES}}$, $V_{\text{CE}} = 0\text{V}$	—	—	2.0	μA
Gate-Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$I_C = 7.5\text{mA}$, $V_{\text{CE}} = 10\text{V}$	5.5	7.0	8.5	Volts
Collector-Emitter Saturation Voltage	$V_{\text{CE(sat)}}$	$I_C = 75\text{A}$, $V_{\text{GE}} = 15\text{V}$, $T_j = 25^\circ\text{C}$ * ³	—	2.2	2.8	Volts
		$I_C = 75\text{A}$, $V_{\text{GE}} = 15\text{V}$, $T_j = 125^\circ\text{C}$ * ³	—	2.45	—	Volts
Total Gate Charge	Q_G	$V_{\text{CC}} = 1000\text{V}$, $I_C = 75\text{A}$, $V_{\text{GE}} = 15\text{V}$	—	500	—	nC
Emitter-Collector Voltage	V_{EC}^{*1}	$I_E = 75\text{A}$, $V_{\text{GE}} = 0\text{V}$ * ³	—	—	3.0	Volts

Dynamic Electrical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	C_{ies}	$V_{\text{CE}} = 10\text{V}$, $V_{\text{GE}} = 0\text{V}$	—	—	18.5	nf
Output Capacitance	C_{oes}		—	—	2.1	nf
Reverse Transfer Capacitance	C_{res}		—	—	0.4	nf
Inductive	Turn-on Delay Time	$V_{\text{CC}} = 1000\text{V}$, $I_C = 75\text{A}$, $V_{\text{GE1}} = V_{\text{GE2}} = 15\text{V}$, $R_G = 6.4\Omega$, Inductive Load	—	—	200	ns
Load	Rise Time		—	—	150	ns
Switch	Turn-off Delay Time		—	—	550	ns
Time	Fall Time		—	—	350	ns
Diode Reverse Recovery Time	t_{rr}^{*1}	Switching Operation,	—	—	300	ns
Diode Reverse Recovery Charge	Q_{rr}^{*1}	$I_E = 75\text{A}$	—	7.5	—	μC

*¹ Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).

*² Pulse width and repetition rate should be such that device junction temperature (T_j) does not exceed $T_{j(\text{max})}$ rating.

*³ Pulse width and repetition rate should be such as to cause negligible temperature rise.

*⁴ Case temperature (T_C), and heatsink temperature (T_f) measured point is just under the chips.

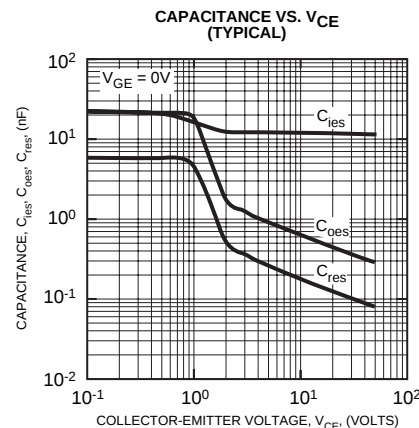
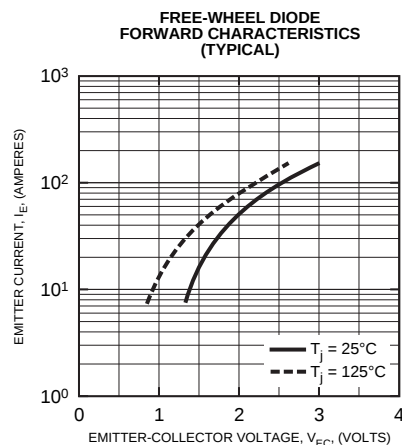
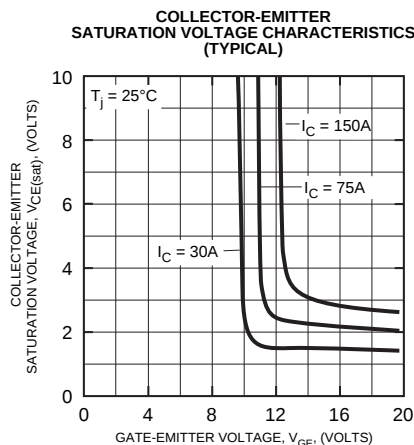
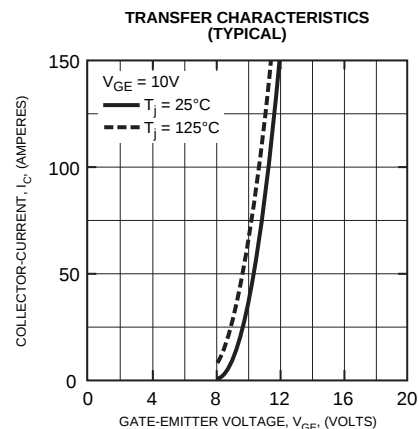
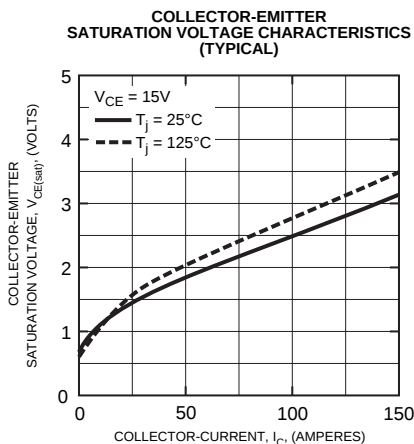
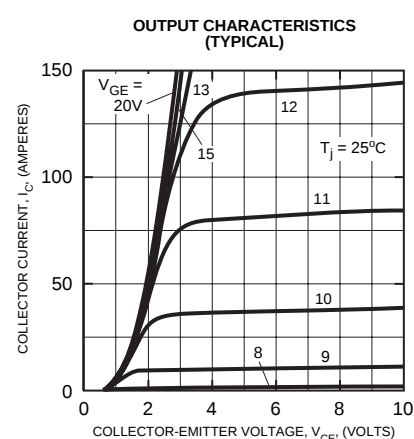
CM75DY-34A
Dual IGBTMOD™ A-Series Module
 75 Amperes/1700 Volts

Thermal and Mechanical Characteristics, $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)Q}$	Per IGBT 1/2 Module*4	—	—	0.16	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)D}$	Per FWDi 1/2 Module*4	—	—	0.29	$^\circ\text{C/W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Thermal Grease Applied*4,*5	—	—	—	$^\circ\text{C/W}$
External Gate Resistance	R_G		6.4	—	64	Ω

*4 Case temperature (T_C), and heatsink temperature (T_f) measured point is just under the chips.

*5 Typical value is measured by using thermally conductive grease of $\lambda = 0.9 \text{ [W/(m} \cdot \text{K)]}$.



CM75DY-34A

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